

# **SOT-23 Plastic-Encapsulate MOSFETS**

#### 30V N-Channel MOSFET

V <sub>(BR)DSS</sub>	R <sub>DS(on)</sub> MAX	Ι <sub>D</sub>
30V	28 mΩ@10V	5A
	34 mΩ@4.5V	36

# **SOT-23** 1. GATE 2. SOURCE 3. DRAIN

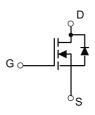
#### **Features**

Lead free product is acquired Surface mount package

#### **MARKING**



#### **Equivalent circuit**



#### **PACKAGE SPECIFICATIONS**

Package	Reel Size	Reel DIA. (mm)	Q'TY/Reel (pcs)	Box Size (mm)	QTY/Box (pcs)	Carton Size (mm)	Q'TY/Carton (pcs)
SOT-23	7'	178	3000	203×203×195	45000	438×438×220	180000

#### Maximum Ratings and Thermal Characteristics (TA = 25°C unless otherwise noted)

Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V <sub>DS</sub>	30		
Gate-Source Voltage	V <sub>GS</sub>	±16	V	
Continuous Drain Current	T <b>a=25</b> ℃	1	5.0	Α
	T <b>a=</b> 70°C	— I <sub>D</sub>	4	
Maximum Power Dissipation 2)	T <b>a=25</b> ℃	В	1.5	۱۸/
	T <b>a=70</b> ℃	P <sub>D</sub>	0.9	W
Pulsed Drain Current 1)	I <sub>DM</sub>	20.4	Α	
Operating Junction and Storage Temperatu	T <sub>J</sub> , T <sub>stg</sub>	-50 to 150	°C	
Thermal Resistance Junction-Ambient	R <sub>θJA</sub>	80	°C/W	

- 1) Pulse width limited by maximum junction temperature.
  2) Surface Mounted on FR4 Board, t ≤ 5 sec.

The above data are for reference only.



# **MOSFET ELECTRICAL CHARACTERISTICS**

# T<sub>a</sub>=25 ℃ unless otherwise specified

Parameter	Symbol	Test Condition	Min.	Тур.	Miax.	Unit	
Static							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250uA	30			V	
		V <sub>GS</sub> = 10V, I <sub>D</sub> = 4.0A		28	36		
Drain-Source On-State Resistance 1)	R <sub>DS(on)</sub>	$V_{GS} = 4.5V, I_D = 3.0A$		34	50	mΩ	
		$V_{GS} = 2.5V, I_D = 1.0A$		55	80		
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}$ , $I_D = 250uA$	0.5	0.8	1.2	V	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	VDS=30V, VGS=0V			1	uA	
Gate Body Leakage	I <sub>GSS</sub>	V <sub>GS</sub> =±16V, V <sub>DS</sub> =0V			100	nA	
Forward Transconductance <sup>1)</sup>	g <sub>fs</sub>	V <sub>DS</sub> =15V, I <sub>D</sub> = 4A		8	_	S	
Dynamic							
Total Gate Charge	Qg			3.1		nC	
Gate-Source Charge	$Q_{gs}$	$V_{DS} = 15V, I_D = 4A$ $V_{GS} = 4.5V$		0.4			
Gate-Drain Charge	$Q_{gd}$	V <sub>GS</sub> - 4.5V		1.3			
Turn-On Delay Time	t <sub>d(on)</sub>			4.4			
Turn-On Rise Time	t <sub>r</sub>	V <sub>DD</sub> = 15V, R <sub>G</sub> =3.3 Ω		2.6		1	
Turn-Off Delay Time	t <sub>d(off)</sub>	I <sub>D</sub> = 1A,V <sub>GS</sub> = 10V		25.5		ns	
Turn-Off Fall Time	t <sub>f</sub>			3.3			
Input Capacitance	C <sub>iss</sub>	\\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \		240			
Output Capacitance	Coss	$V_{DS} = 15V, V_{GS} = 0V$		35		pF	
Reverse Transfer Capacitance	C <sub>rss</sub>	1 - 1.0 NIMZ		30			
Source drain current(Body Diode)	Isp				1.8	Α	
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> = 4.0A, V <sub>GS</sub> = 0V		0.85	1.2	V	

<sup>&</sup>lt;sup>1)</sup> Pulse test : Pulse width≤300μs, duty cycle≤2%.



## **Typical Characteristics**

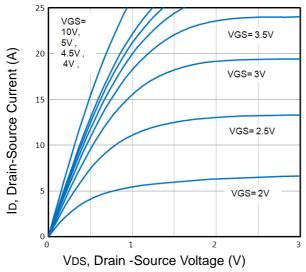


Fig1. Typical Output Characteristics

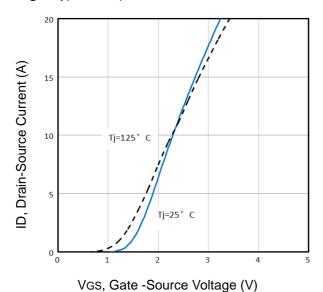


Fig3. Typical Transfer Characteristics

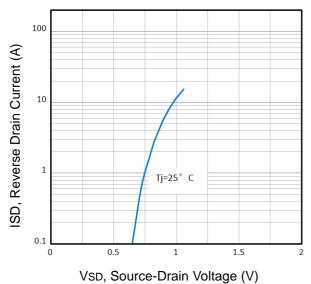


Fig5. Typical Source-Drain Diode Forward Voltage

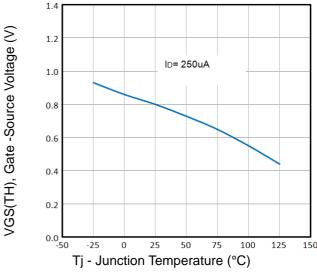


Fig2. Normalized Threshold Voltage Vs. Temperature

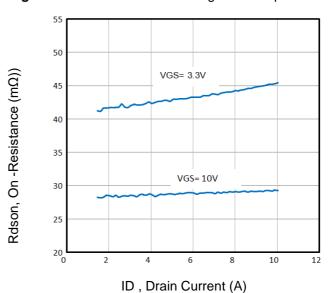


Fig4. On-Resistance vs. Drain Current and Gate

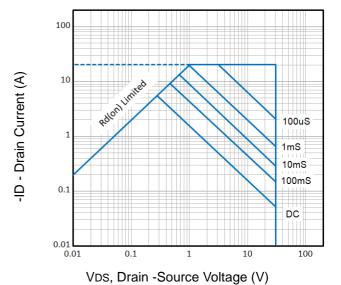


Fig6. Maximum Safe Operating Area

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## **Typical Characteristics**

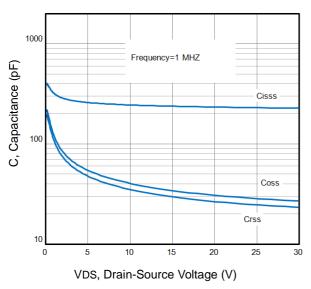


Fig7. Typical Capacitance Vs. Drain-Source Voltage

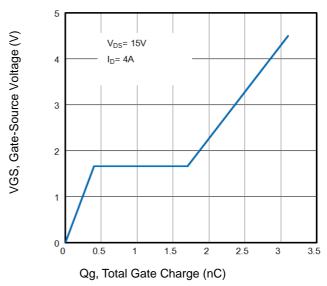


Fig8. Typical Gate Charge Vs. Gate-Source Voltage

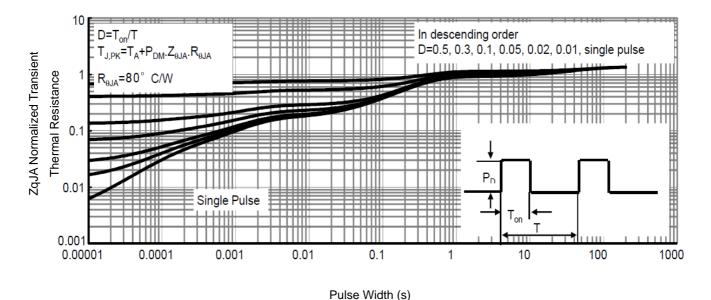


Fig9. Normalized Maximum Transient Thermal Impedance

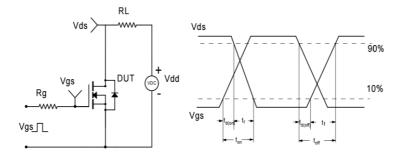


Fig10. Switching Time Test Circuit and waveforms

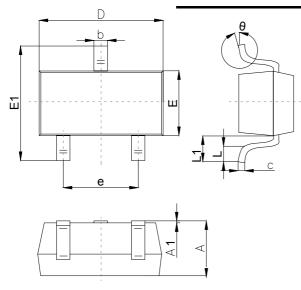
The curve above is for reference only.

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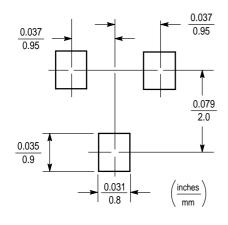
# **Outlitne Drawing**

#### SOT-23 Package Outline Dimensions



Symbol	Dimensions In Millimeters			
Symbol	Min	Тур	Max	
Α	1.00		1.40	
A1			0.10	
b	0.35		0.50	
С	0.10		0.20	
D	2.70	2.90	3.10	
Е	1.40		1.60	
E1	2.4		2.80	
е		1.90		
L	0.10		0.30	
L1	0.4			
θ	0°		10°	

# **Suggested Pad Layout**



#### Note:

- 1. Controlling dimension: in/millimeters.
- 2.General tolerance: ±0.05mm.
- 3. The pad layout is for reference purposes only.

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